

3.0 KP BIPOLAR TRANSIENT VOLTAGE SUPPRESSOR DIODE CELLS

FEATURES

- Lowest Electrical & Thermal Resistance - Ideally Suited For Preventing Overvoltage/Overcurrent Damage to Power over Ethernet (PoE) Equipment
- VOID FREE VACUUM DIE SOLDERING For Lowest Electrical/Thermal Resistance And Maximum Mechanical Strength & Heat Dissipation (Solder Voids: Typical $\leq 2\%$, Max. $\leq 10\%$ of Die Area)
- Round Die For High Power Heavy Duty Performance
- High Heat Handling Capability With Very Low Thermal Stress
- Proprietary Junction Passivation For Superior Reliability And Performance

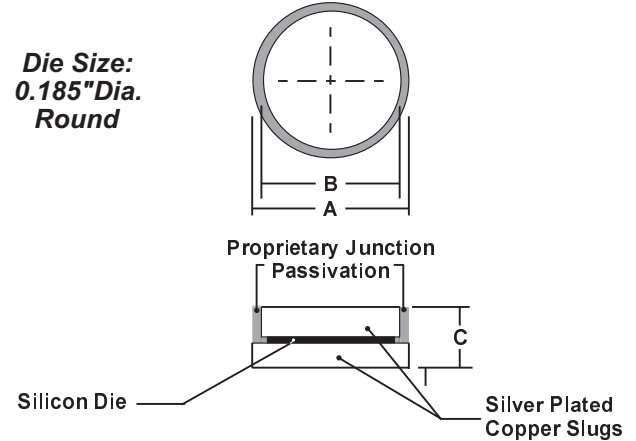
RoHS COMPLIANT

MECHANICAL DATA

- Finish: All external surfaces are silver plated for corrosion resistance superior solderability
- Soldering Temperature: 282 °C maximum
- Mounting Position: Any
- Polarity: Bipolar

MECHANICAL SPECIFICATION

Die Size:
 0.185" Dia.
 Round



DIM	INCHES	
	NOM	+/-
A	0.215	0.003
B	0.190	0.003
C	0.083	0.004

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

PARAMETER	SYMBOL	RATINGS	UNITS
Series Number		BP3-23	
Breakdown Voltage (Cells Begin to Conduct) (See Note 1)	V _{BR}	23.3 Min +/- 5%	VOLTS
Test Current (To Determine V _{BR})	I _T	2.0	mA
Clamping Voltage During a 10/1000 μ S Transient	V _{C(10)}	33 (Max)	VOLTS
Maximum Current Conducted During a 10/1000 μ S Transient	I _{PPM(10)}	91 Min	AMPS
Reverse Stand Off Voltage (Voltage at Which I _R Measured)	V _{WM}	20	VOLTS
Maximum Current Conducted at V _{WM}	I _R	2	μ A
Maximum Current Conducted During 8/20 μ S Transient	I _{PPM(8)}	800 Min	AMPS
Clamping Voltage During 8/20 μ S Transient	V _{C(8)}	37.5 Max	VOLTS

Notes: (1) Diode cell breakdown voltage can be tailored to meet your specific application requirements. Please Contact Us for details.